Intel - 5SGXEA7N1F40I2 Datasheet





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Details

Product Status	Obsolete
Number of LABs/CLBs	234720
Number of Logic Elements/Cells	622000
Total RAM Bits	51200000
Number of I/O	600
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1517-BBGA, FCBGA
Supplier Device Package	1517-FBGA (40x40)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxea7n1f40i2

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Table 5 lists the maximum allowed input overshoot voltage and the duration of the overshoot voltage as a percentage of device lifetime. The maximum allowed overshoot duration is specified as a percentage of high time over the lifetime of the device. A DC signal is equivalent to 100% of the duty cycle. For example, a signal that overshoots to 3.95 V can be at 3.95 V for only ~21% over the lifetime of the device; for a device lifetime of 10 years, the overshoot duration amounts to ~2 years.

Symbol	Description	Condition (V)	Overshoot Duration as % @ T _J = 100°C	Unit						
		3.8	100	%						
		3.85	64	%						
		3.9	36	%						
		3.95	21	%						
Vi (AC)	AC input voltage	4	12	%						
		4.05	7	%						
		4.1	4	%						
		4.15	2	%						
		4.2	1	%						

Table 5. Maximum Allowed Overshoot During Transitions

Figure 1. Stratix V Device Overshoot Duration



This section lists the functional operating limits for the AC and DC parameters for Stratix V devices. Table 6 lists the steady-state voltage and current values expected from Stratix V devices. Power supply ramps must all be strictly monotonic, without plateaus.

Table 6. Recommended Operating Conditions for Stratix V Devices (Part 1 of 2)

Symbol	Description	Condition	Min ⁽⁴⁾	Тур	Max ⁽⁴⁾	Unit
	Core voltage and periphery circuitry power supply (C1, C2, I2, and I3YY speed grades)	_	0.87	0.9	0.93	V
V _{CC}	Core voltage and periphery circuitry power supply (C2L, C3, C4, I2L, I3, I3L, and I4 speed grades) ⁽³⁾	_	0.82	0.85	0.88	V
V _{CCPT}	Power supply for programmable power technology	_	1.45	1.50	1.55	V
V _{CC_AUX}	Auxiliary supply for the programmable power technology	_	2.375	2.5	2.625	V
VI (1)	I/O pre-driver (3.0 V) power supply	_	2.85	3.0	3.15	V
V _{CCPD} ⁽¹⁾	I/O pre-driver (2.5 V) power supply	_	2.375	2.5	2.625	V
	I/O buffers (3.0 V) power supply		2.85	3.0	3.15	V
	I/O buffers (2.5 V) power supply	_	2.375	2.5	2.625	V
	I/O buffers (1.8 V) power supply		1.71	1.8	1.89	V
V _{CCIO}	I/O buffers (1.5 V) power supply	_	1.425	1.5	1.575	V
	I/O buffers (1.35 V) power supply	_	1.283	1.35	1.45	V
	I/O buffers (1.25 V) power supply	_	1.19	1.25	1.31	V
	I/O buffers (1.2 V) power supply	_	1.14	1.2	1.26	V
	Configuration pins (3.0 V) power supply	_	2.85	3.0	3.15	V
V _{CCPGM}	Configuration pins (2.5 V) power supply	_	2.375	2.5	2.625	V
	Configuration pins (1.8 V) power supply	_	1.71	1.8	1.89	V
V _{CCA_FPLL}	PLL analog voltage regulator power supply	_	2.375	2.5	2.625	V
V _{CCD_FPLL}	PLL digital voltage regulator power supply	_	1.45	1.5	1.55	V
V _{CCBAT} (2)	Battery back-up power supply (For design security volatile key register)	_	1.2	_	3.0	V
VI	DC input voltage	_	-0.5	_	3.6	V
V ₀	Output voltage	—	0	—	V _{CCIO}	V
т	Operating junction temperature	Commercial	0	—	85	°C
TJ	Operating junction temperature	Industrial	-40	_	100	°C

Symbol	Description	Condition	Min ⁽⁴⁾	Тур	Max ⁽⁴⁾	Unit
+	Power supply ramp time	Standard POR	200 µs	_	100 ms	—
LRAMP	Power supply ramp time	Fast POR	200 µs		4 ms	_

Table 6. Recommended Operating Conditions for Stratix V Devices (Part 2 of 2)

Notes to Table 6:

(1) V_{CCPD} must be 2.5 V when V_{CCI0} is 2.5, 1.8, 1.5, 1.35, 1.25 or 1.2 V. V_{CCPD} must be 3.0 V when V_{CCI0} is 3.0 V.

(2) If you do not use the design security feature in Stratix V devices, connect V_{CCBAT} to a 1.2- to 3.0-V power supply. Stratix V power-on-reset (POR) circuitry monitors V_{CCBAT}. Stratix V devices will not exit POR if V_{CCBAT} stays at logic low.

(3) C2L and I2L can also be run at 0.90 V for legacy boards that were designed for the C2 and I2 speed grades.

(4) The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

Table 7 lists the transceiver power supply recommended operating conditions for Stratix V GX, GS, and GT devices.

Table 7. Recommended Transceiver Power Supply Operating Conditions for Stratix V GX, GS, and GT Devices (Part 1 of 2)

Symbol	Description	Devices	Minimum ⁽⁴⁾	Typical	Maximum ⁽⁴⁾	Unit
V _{CCA_GXBL}	Transceiver channel PLL power supply (left	GX, GS, GT	2.85	3.0	3.15	V
(1), (3)	side)	un, uo, ui	2.375	2.5	2.625	v
V _{CCA_GXBR}	Transceiver channel PLL power supply (right	GX, GS	2.85	3.0	3.15	V
(1), (3)	side)		2.375	2.5	2.625	v
V _{CCA_GTBR}	Transceiver channel PLL power supply (right side)	GT	2.85	3.0	3.15	V
	Transceiver hard IP power supply (left side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
V _{CCHIP_L}	Transceiver hard IP power supply (left side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
	Transceiver hard IP power supply (right side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
V _{CCHIP_R}	Transceiver hard IP power supply (right side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
	Transceiver PCS power supply (left side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
V _{CCHSSI_L}	Transceiver PCS power supply (left side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
	Transceiver PCS power supply (right side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
V _{CCHSSI_R}	Transceiver PCS power supply (right side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
			0.82	0.85	0.88	
V _{CCR_GXBL}	Pacaivar analog powar supply (left side)		0.87	0.90	0.93	V
(2)	Receiver analog power supply (left side)	GX, GS, GT	0.97	1.0	1.03	v
			1.03	1.05	1.07	

Symbol	Description	Devices	Minimum ⁽⁴⁾	Typical	Maximum ⁽⁴⁾	Unit
			0.82	0.85	0.88	
V _{CCR_GXBR}	Receiver analog power supply (right side)	GX, GS, GT	0.87	0.90	0.93	v
(2)	Receiver analog power supply (right side)	un, us, ui	0.97	1.0	1.03	v
			1.03	1.05	1.07	
V _{CCR_GTBR}	Receiver analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
			0.82	0.85	0.88	
V _{CCT_GXBL}	Transmitter analog newer supply (left side)	GX, GS, GT	0.87	0.90	0.93	V
(2)	Transmitter analog power supply (left side)		0.97	1.0	1.03	
			1.03	1.05	1.07	
		GX, GS, GT	0.82	0.85	0.88	V
V _{CCT_GXBR}	Transmitter analog nower supply (right side)		0.87	0.90	0.93	
(2)	Transmitter analog power supply (right side)		0.97	1.0	1.03	
			1.03	1.05	1.07	
V _{CCT_GTBR}	Transmitter analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
V_{CCL_GTBR}	Transmitter clock network power supply	GT	1.02	1.05	1.08	V
V _{CCH_GXBL}	Transmitter output buffer power supply (left side)	GX, GS, GT	1.425	1.5	1.575	V
V _{CCH_GXBR}	Transmitter output buffer power supply (right side)	GX, GS, GT	1.425	1.5	1.575	V

Table 7.	Recommended Transceiver Power Supply Operating Conditions for Stratix V GX,	GS, and GT Devices
(Part 2	of 2)	

Notes to Table 7:

(1) This supply must be connected to 3.0 V if the CMU PLL, receiver CDR, or both, are configured at a base data rate > 6.5 Gbps. Up to 6.5 Gbps, you can connect this supply to either 3.0 V or 2.5 V.

(2) Refer to Table 8 to select the correct power supply level for your design.

(3) When using ATX PLLs, the supply must be 3.0 V.

(4) This value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

Table 8 shows the transceiver power supply voltage requirements for various conditions.

Table 8. Transceiver Power Supply Voltage Requirements

Conditions	Core Speed Grade	VCCR_GXB & VCCT_GXB ⁽²⁾	VCCA_GXB	VCCH_GXB	Unit
If BOTH of the following conditions are true:	All	1.05			
 Data rate > 10.3 Gbps. DFE is used. 	All	1.05			
If ANY of the following conditions are true ⁽¹⁾ :			3.0		
ATX PLL is used.					
■ Data rate > 6.5Gbps.	All	1.0			
■ DFE (data rate ≤ 10.3 Gbps), AEQ, or EyeQ feature is used.				1.5	V
If ALL of the following	C1, C2, I2, and I3YY	0.90	2.5		
conditions are true:ATX PLL is not used.					
■ Data rate ≤ 6.5Gbps.	C2L, C3, C4, I2L, I3, I3L, and I4	0.85	2.5		
 DFE, AEQ, and EyeQ are not used. 					

Notes to Table 8:

(1) Choose this power supply voltage requirement option if you plan to upgrade your design later with any of the listed conditions.

(2) If the VCCR_GXB and VCCT_GXB supplies are set to 1.0 V or 1.05 V, they cannot be shared with the VCC core supply. If the VCCR_GXB and VCCT_GXB are set to either 0.90 V or 0.85 V, they can be shared with the VCC core supply.

DC Characteristics

This section lists the supply current, I/O pin leakage current, input pin capacitance, on-chip termination tolerance, and hot socketing specifications.

Supply Current

Supply current is the current drawn from the respective power rails used for power budgeting. Use the Excel-based Early Power Estimator (EPE) to get supply current estimates for your design because these currents vary greatly with the resources you use.

For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in the *Quartus II Handbook*.

I/O Standard	V _{IL(DI}	_{c)} (V)	V _{IH(D}	_{C)} (V)	V _{IL(AC)} (V)	V _{IH(AC)} (V)	V _{ol} (V)	V _{oh} (V)	I (mA)	I _{oh}
i/U Stanuaru	Min	Max	Min	Max	Max	Min	Max	Min	l _{oi} (mA)	(mA)
HSTL-18 Class I	_	V _{REF} – 0.1	V _{REF} + 0.1	_	$V_{REF} - 0.2$	V _{REF} + 0.2	0.4	V _{CCIO} – 0.4	8	-8
HSTL-18 Class II	_	V _{REF} – 0.1	V _{REF} + 0.1	_	V _{REF} - 0.2	V _{REF} + 0.2	0.4	V _{CCIO} – 0.4	16	-16
HSTL-15 Class I	_	V _{REF} – 0.1	V _{REF} + 0.1	_	V _{REF} - 0.2	V _{REF} + 0.2	0.4	V _{CCIO} – 0.4	8	-8
HSTL-15 Class II	_	V _{REF} – 0.1	V _{REF} + 0.1	_	V _{REF} - 0.2	V _{REF} + 0.2	0.4	V _{CCIO} – 0.4	16	-16
HSTL-12 Class I	-0.15	V _{REF} – 0.08	V _{REF} + 0.08	V _{CCIO} + 0.15	V _{REF} – 0.15	V _{REF} + 0.15	0.25* V _{CCI0}	0.75* V _{CCI0}	8	-8
HSTL-12 Class II	-0.15	V _{REF} – 0.08	V _{REF} + 0.08	V _{CCIO} + 0.15	V _{REF} – 0.15	V _{REF} + 0.15	0.25* V _{CCIO}	0.75* V _{CCI0}	16	-16
HSUL-12	_	V _{REF} – 0.13	V _{REF} + 0.13	_	V _{REF} – 0.22	V _{REF} + 0.22	0.1* V _{CCIO}	0.9* V _{CCI0}	_	_

Table 19. Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications for Stratix V Devices (Part 2 of 2)

Table 20. Differential SSTL I/O Standards for Stratix V Devices

I/O Standard		V _{ccio} (V)		V _{SWIN}	_{G(DC)} (V)		V _{X(AC)} (V)			V _{SWING(AC)} (V)	
ijo Stanuaru	Min	Тур	Max	Min	Max	Min	Тур	Max	Min	Max	
SSTL-2 Class I, II	2.375	2.5	2.625	0.3	V _{CCI0} + 0.6	V _{CCI0} /2- 0.2	_	V _{CCI0} /2 + 0.2	0.62	V _{CCI0} + 0.6	
SSTL-18 Class I, II	1.71	1.8	1.89	0.25	V _{CCI0} + 0.6	V _{CCI0} /2- 0.175	_	V _{CCI0} /2 + 0.175	0.5	V _{CCI0} + 0.6	
SSTL-15 Class I, II	1.425	1.5	1.575	0.2	(1)	V _{CCI0} /2- 0.15	_	V _{CCI0} /2 + 0.15	0.35	_	
SSTL-135 Class I, II	1.283	1.35	1.45	0.2	(1)	V _{CCI0} /2- 0.15	V _{CCI0} /2	V _{CCI0} /2 + 0.15	2(V _{IH(AC)} - V _{REF})	2(V _{IL(AC)} - V _{REF})	
SSTL-125 Class I, II	1.19	1.25	1.31	0.18	(1)	V _{CCI0} /2- 0.15	V _{CCI0} /2	V _{CCI0} /2 + 0.15	2(V _{IH(AC)} - V _{REF})	_	
SSTL-12 Class I, II	1.14	1.2	1.26	0.18	_	V _{REF} -0.15	V _{CCI0} /2	V _{REF} + 0.15	-0.30	0.30	

Note to Table 20:

(1) The maximum value for $V_{SWING(DC)}$ is not defined. However, each single-ended signal needs to be within the respective single-ended limits $(V_{IH(DC)} \text{ and } V_{IL(DC)})$.

I/O	V _{CCIO} (V)			V _{DIF(I}	_{DC)} (V)	V _{X(AC)} (V)			V _{CM(DC)} (V)			V _{DIF(AC)} (V)	
Standard	Min	Тур	Max	Min	Max	Min	Тур	Max	Min	Тур	Max	Min	Max
HSTL-18 Class I, II	1.71	1.8	1.89	0.2	_	0.78	_	1.12	0.78	_	1.12	0.4	_
HSTL-15 Class I, II	1.425	1.5	1.575	0.2	_	0.68	_	0.9	0.68	_	0.9	0.4	_

Symbol/	Conditions	Tra	nsceive Grade	r Speed 1	Trai	nsceive Grade	r Speed 2	Trar	isceive Grade	r Speed 3	Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
	DC Gain Setting = 0		0	_	_	0		_	0	—	dB
	DC Gain Setting = 1	_	2	_	—	2	_	_	2	_	dB
Programmable DC gain	DC Gain Setting = 2	_	4	_	_	4	_	_	4	_	dB
	DC Gain Setting = 3	_	6	_	_	6	_	_	6	_	dB
	DC Gain Setting = 4	_	8	_	_	8	_	_	8	—	dB
Transmitter											
Supported I/O Standards	_	1.4-V and 1.5-V PCML									
Data rate (Standard PCS)	_	600	_	12200	600	_	12200	600	_	8500/ 10312.5 (24)	Mbps
Data rate (10G PCS)	_	600	_	14100	600		12500	600		8500/ 10312.5 (24)	Mbps
	85-Ω setting		85 ± 20%	_	_	85 ± 20%		_	85 ± 20%	_	Ω
Differential on-	100-Ω setting	_	100 ± 20%	_	_	100 ± 20%	_	_	100 ± 20%	_	Ω
chip termination resistors	120-Ω setting	_	120 ± 20%			120 ± 20%		_	120 ± 20%		Ω
	150-Ω setting		150 ± 20%			150 ± 20%			150 ± 20%		Ω
V _{OCM} (AC coupled)	0.65-V setting		650		_	650		_	650	_	mV
V _{OCM} (DC coupled)	_		650		_	650		_	650	_	mV
Rise time (7)	20% to 80%	30		160	30		160	30		160	ps
Fall time ⁽⁷⁾	80% to 20%	30		160	30		160	30		160	ps
Intra-differential pair skew	Tx V _{CM} = 0.5 V and slew rate of 15 ps			15			15			15	ps
Intra-transceiver block transmitter channel-to- channel skew	x6 PMA bonded mode			120			120			120	ps

Table 23. Transceiver Specifications for Stratix V GX and GS Devices ⁽¹⁾ (Part 5 of 7)

Symbol/ Description		Trai	Transceiver Speed Grade 1			Transceiver Speed Grade 2			Transceiver Speed Grade 3		
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
t _{pll_lock} (16)	_			10		—	10	—		10	μs

Table 23. Transceiver Specifications for Stratix V GX and GS Devices ⁽¹⁾ (Part 7 of 7)

Notes to Table 23:

(2) The reference clock common mode voltage is equal to the V_{CCR_GXB} power supply level.

(3) This supply must be connected to 1.0 V if the transceiver is configured at a data rate > 6.5 Gbps, and to 1.05 V if configured at a data rate > 10.3 Gbps when DFE is used. For data rates up to 6.5 Gbps, you can connect this supply to 0.85 V.

- (4) This supply follows VCCR_GXB.
- (5) The device cannot tolerate prolonged operation at this absolute maximum.
- (6) The differential eye opening specification at the receiver input pins assumes that **Receiver Equalization** is disabled. If you enable **Receiver Equalization**, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.
- (7) The Quartus II software automatically selects the appropriate slew rate depending on the configured data rate or functional mode.
- (8) The input reference clock frequency options depend on the data rate and the device speed grade.
- (9) The line data rate may be limited by PCS-FPGA interface speed grade.
- (10) Refer to Figure 1 for the GX channel AC gain curves. The total effective AC gain is the AC gain minus the DC gain.
- (11) t_{LTR} is the time required for the receive CDR to lock to the input reference clock frequency after coming out of reset.
- (12) t_{LTD} is time required for the receiver CDR to start recovering valid data after the rx_is_lockedtodata signal goes high.
- (13) t_{LTD_manual} is the time required for the receiver CDR to start recovering valid data after the rx_is_lockedtodata signal goes high when the CDR is functioning in the manual mode.
- (14) $t_{LTR_LTD_manual}$ is the time the receiver CDR must be kept in lock to reference (LTR) mode after the rx_is_lockedtoref signal goes high when the CDR is functioning in the manual mode.
- (15) $t_{pll_powerdown}$ is the PLL powerdown minimum pulse width.
- (16) t_{pll lock} is the time required for the transmitter CMU/ATX PLL to lock to the input reference clock frequency after coming out of reset.
- (17) To calculate the REFCLK rms phase jitter requirement for PCIe at reference clock frequencies other than 100 MHz, use the following formula: REFCLK rms phase jitter at f(MHz) = REFCLK rms phase jitter at 100 MHz × 100/f.
- (18) The maximum peak to peak differential input voltage V_{ID} after device configuration is equal to 4 × (absolute V_{MAX} for receiver pin V_{ICM}).
- (19) For ES devices, R_{BEF} is 2000 $\Omega \pm 1\%$.
- (20) To calculate the REFCLK phase noise requirement at frequencies other than 622 MHz, use the following formula: REFCLK phase noise at f(MHz) = REFCLK phase noise at 622 MHz + 20*log(f/622).
- (21) SFP/+ optical modules require the host interface to have RD+/- differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.
- (22) Refer to Figure 2.
- (23) For oversampling designs to support data rates less than the minimum specification, the CDR needs to be in LTR mode only.
- (24) I3YY devices can achieve data rates up to 10.3125 Gbps.
- (25) When you use fPLL as a TXPLL of the transceiver.
- (26) REFCLK performance requires to meet transmitter REFCLK phase noise specification.
- (27) Minimum eye opening of 85 mV is only for the unstressed input eye condition.

⁽¹⁾ Speed grades shown in Table 23 refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the Stratix V Device Overview.

Table 27 shows the V_{OD} settings for the GX channel.

Symbol	V _{op} Setting	V _{op} Value (mV)	V _{op} Setting	V _{op} Value (mV)
	0 (1)	0	32	640
	1 ⁽¹⁾	20	33	660
	2 (1)	40	34	680
	3 (1)	60	35	700
	4 (1)	80	36	720
	5 (1)	100	37	740
	6	120	38	760
	7	140	39	780
	8	160	40	800
	9	180	41	820
	10	200	42	840
	11	220	43	860
	12	240	44	880
	13	260	45	900
	14	280	46	920
V _{op} differential peak to peak	15	300	47	940
typical ⁽³⁾	16	320	48	960
	17	340	49	980
	18	360	50	1000
	19	380	51	1020
	20	400	52	1040
	21	420	53	1060
	22	440	54	1080
	23	460	55	1100
	24	480	56	1120
	25	500	57	1140
	26	520	58	1160
	27	540	59	1180
	28	560	60	1200
	29	580	61	1220
	30	600	62	1240
	31	620	63	1260

Table 27. Typical V_{0D} Setting for GX Channel, TX Termination = 100 $\Omega^{\left(2\right)}$

Note to Table 27:

(1) If TX termination resistance = 100Ω , this VOD setting is illegal.

(2) The tolerance is +/-20% for all VOD settings except for settings 2 and below.

(3) Refer to Figure 2.

Symbol/	Conditions	5	Transceiver Speed Grade			Transceive peed Grade		Unit
Description		Min	Тур	Max	Min	Тур	Max	
Differential on-chip termination resistors ⁽⁷⁾	GT channels		100	_	_	100	_	Ω
	85- Ω setting	_	85 ± 30%	_	_	85 ± 30%	_	Ω
Differential on-chip termination resistors for GX channels ⁽¹⁹⁾	100-Ω setting	_	100 ± 30%	_	_	100 ± 30%	_	Ω
	120-Ω setting	_	120 ± 30%	_	_	120 ± 30%	_	Ω
	150-Ω setting		150 ± 30%	_	_	150 ± 30%	_	Ω
V _{ICM} (AC coupled)	GT channels		650		—	650	—	mV
	VCCR_GXB = 0.85 V or 0.9 V		600	_	_	600		mV
VICM (AC and DC coupled) for GX Channels	VCCR_GXB = 1.0 V full bandwidth	_	700	_	_	700	_	mV
	VCCR_GXB = 1.0 V half bandwidth		750	_	_	750	_	mV
t _{LTR} ⁽⁹⁾	—	—	—	10	—	—	10	μs
t _{LTD} ⁽¹⁰⁾		4			4			μs
t _{LTD_manual} ⁽¹¹⁾	—	4	—	—	4	—	_	μs
t _{LTR_LTD_manual} ⁽¹²⁾	_	15			15	—		μs
Run Length	GT channels	_	_	72	—	—	72	CID
nun Lengin	GX channels				(8)			
CDR PPM	GT channels			1000	_	—	1000	± PPM
	GX channels				(8)			
Programmable	GT channels	_	_	14	—	—	14	dB
equalization (AC Gain) ⁽⁵⁾	GX channels				(8)			
Programmable	GT channels	_	—	7.5	—	—	7.5	dB
DC gain ⁽⁶⁾	GX channels				(8)			
Differential on-chip termination resistors ⁽⁷⁾	GT channels	_	100	_	_	100	_	Ω
Transmitter	·1							
Supported I/O Standards	_			1.4-V	and 1.5-V F	PCML		
Data rate (Standard PCS)	GX channels	600	_	8500	600	_	8500	Mbps
Data rate (10G PCS)	GX channels	600		12,500	600	_	12,500	Mbps

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 3 of 5)⁽¹⁾

Figure 4 shows the differential transmitter output waveform.





Figure 5 shows the Stratix V AC gain curves for GT channels.

Figure 5. AC Gain Curves for GT Channels

PLL Specifications

Table 31 lists the Stratix V PLL specifications when operating in both the commercial junction temperature range (0° to 85° C) and the industrial junction temperature range (-40° to 100° C).

Table 31. PLL Specifications for Stratix V Devices (Part 1 of 3)

Symbol	Parameter	Min	Тур	Max	Unit
	Input clock frequency (C1, C2, C2L, I2, and I2L speed grades)	5	_	800 (1)	MHz
f _{IN}	Input clock frequency (C3, I3, I3L, and I3YY speed grades)	5	_	800 (1)	MHz
	Input clock frequency (C4, I4 speed grades)	5	_	650 ⁽¹⁾	MHz
f _{INPFD}	Input frequency to the PFD	5	—	325	MHz
f _{finpfd}	Fractional Input clock frequency to the PFD	50	_	160	MHz
	PLL VCO operating range (C1, C2, C2L, I2, I2L speed grades)	600	_	1600	MHz
f _{VCO}	PLL VCO operating range (C3, I3, I3L, I3YY speed grades)	600	_	1600	MHz
	PLL VCO operating range (C4, I4 speed grades)	600	—	1300	MHz
t _{einduty}	Input clock or external feedback clock input duty cycle	40		60	%
	Output frequency for an internal global or regional clock (C1, C2, C2L, I2, I2L speed grades)	—	_	717 ⁽²⁾	MHz
f _{out}	Output frequency for an internal global or regional clock (C3, I3, I3L speed grades)	_	_	650 ⁽²⁾	MHz
	Output frequency for an internal global or regional clock (C4, I4 speed grades)	_	_	580 ⁽²⁾	MHz
	Output frequency for an external clock output (C1, C2, C2L, I2, I2L speed grades)	_	_	800 (2)	MHz
f _{out_ext}	Output frequency for an external clock output (C3, I3, I3L speed grades)	_	_	667 ⁽²⁾	MHz
	Output frequency for an external clock output (C4, I4 speed grades)	_	_	553 ⁽²⁾	MHz
t _{outduty}	Duty cycle for a dedicated external clock output (when set to 50%)	45	50	55	%
t _{FCOMP}	External feedback clock compensation time	_	—	10	ns
f _{dyconfigclk}	Dynamic Configuration Clock used for <code>mgmt_clk</code> and <code>scanclk</code>	_	_	100	MHz
t _{LOCK}	Time required to lock from the end-of-device configuration or deassertion of areset	_	_	1	ms
t _{olock}	Time required to lock dynamically (after switchover or reconfiguring any non-post-scale counters/delays)	_	_	1	ms
	PLL closed-loop low bandwidth		0.3	—	MHz
f _{CLBW}	PLL closed-loop medium bandwidth	_	1.5		MHz
	PLL closed-loop high bandwidth (7)		4	—	MHz
t _{PLL_PSERR}	Accuracy of PLL phase shift			±50	ps
t _{areset}	Minimum pulse width on the areset signal	10	_		ns

Symbol	Parameter	Min	Тур	Max	Unit
+ (3) (4)	Input clock cycle-to-cycle jitter ($f_{REF} \ge 100 \text{ MHz}$)	_	—	0.15	UI (p-p)
t _{INCCJ} ^{(3),} ⁽⁴⁾	Input clock cycle-to-cycle jitter (f _{REF} < 100 MHz)	-750	_	+750	ps (p-p)
t	Period Jitter for dedicated clock output (f_{OUT} \geq 100 MHz)	_	_	175 ⁽¹⁾	ps (p-p)
t _{outpj_dc} ⁽⁵⁾	Period Jitter for dedicated clock output (f _{OUT} < 100 MHz)	_		17.5 ⁽¹⁾	mUI (p-p)
+ (5)	Period Jitter for dedicated clock output in fractional PLL ($f_{0UT} \geq 100 \mbox{ MHz})$	_	_	250 ⁽¹¹⁾ , 175 ⁽¹²⁾	ps (p-p)
t _{foutpj_dc} ⁽⁵⁾	Period Jitter for dedicated clock output in fractional PLL (f _{OUT} < 100 MHz)	_	_	25 ⁽¹¹⁾ , 17.5 ⁽¹²⁾	mUI (p-p)
+	Cycle-to-Cycle Jitter for a dedicated clock output ($f_{OUT} \ge 100 \text{ MHz}$)			175	ps (p-p)
t _{outccj_dc} ⁽⁵⁾	Cycle-to-Cycle Jitter for a dedicated clock output (f _{0UT} < 100 MHz)	_	_	17.5	mUI (p-p)
+ <i>(5)</i>	Cycle-to-cycle Jitter for a dedicated clock output in fractional PLL (f_{OUT} \geq 100 MHz)	_	_	250 ⁽¹¹⁾ , 175 ⁽¹²⁾	ps (p-p)
t _{FOUTCCJ_DC} ⁽⁵⁾	Cycle-to-cycle Jitter for a dedicated clock output in fractional PLL ($f_{OUT} < 100 \text{ MHz}$)+	_	_	25 ⁽¹¹⁾ , 17.5 ⁽¹²⁾	mUI (p-p)
t _{outpj_io} (5),	Period Jitter for a clock output on a regular I/O in integer PLL (f_{OUT} \geq 100 MHz)	_	_	600	ps (p-p)
(8)	Period Jitter for a clock output on a regular I/O (f _{OUT} < 100 MHz)	_	_	60	mUI (p-p)
t _{FOUTPJ_IO} (5),	Period Jitter for a clock output on a regular I/O in fractional PLL ($f_{OUT} \ge 100 \text{ MHz}$)	_	_	600 (10)	ps (p-p)
(8), (11)	Period Jitter for a clock output on a regular I/O in fractional PLL (f _{OUT} < 100 MHz)	_	_	60 ⁽¹⁰⁾	mUI (p-p)
t _{outccj_lo} (5),	Cycle-to-cycle Jitter for a clock output on a regular I/O in integer PLL (f_{OUT} \geq 100 MHz)	_	_	600	ps (p-p)
(8)	Cycle-to-cycle Jitter for a clock output on a regular I/O in integer PLL (f_{OUT} < 100 MHz)	_	_	60 ⁽¹⁰⁾	mUI (p-p)
t _{foutccj_10} ^{(5),}	Cycle-to-cycle Jitter for a clock output on a regular I/O in fractional PLL ($f_{0UT} \geq 100 \mbox{ MHz})$	_	_	600 ⁽¹⁰⁾	ps (p-p)
(8), (11)	Cycle-to-cycle Jitter for a clock output on a regular I/O in fractional PLL ($f_{OUT} < 100 \text{ MHz}$)	_	_	60	mUI (p-p)
t _{casc_outpj_dc}	Period Jitter for a dedicated clock output in cascaded PLLs (f_{0UT} \geq 100 MHz)		_	175	ps (p-p)
(5), (6)	Period Jitter for a dedicated clock output in cascaded PLLs (f _{OUT} < 100 MHz)		_	17.5	mUI (p-p)
f _{DRIFT}	Frequency drift after PFDENA is disabled for a duration of 100 μs	_	_	±10	%
dK _{BIT}	Bit number of Delta Sigma Modulator (DSM)	8	24	32	Bits
k _{value}	Numerator of Fraction	128	8388608	2147483648	

Table 31. PLL Specifications for Stratix V Devices (Part 2 of 3)

Table 31. PLL Specifications for Stratix V Devices (Part 3 of 3)

Symbol	Parameter	Min	Тур	Max	Unit
f _{RES}	Resolution of VCO frequency ($f_{INPFD} = 100 \text{ MHz}$)	390625	5.96	0.023	Hz

Notes to Table 31:

(1) This specification is limited in the Quartus II software by the I/O maximum frequency. The maximum I/O frequency is different for each I/O standard.

(2) This specification is limited by the lower of the two: I/O f_{MAX} or f_{OUT} of the PLL.

- (3) A high input jitter directly affects the PLL output jitter. To have low PLL output clock jitter, you must provide a clean clock source < 120 ps.
- (4) f_{REF} is fIN/N when N = 1.
- (5) Peak-to-peak jitter with a probability level of 10⁻¹² (14 sigma, 99.9999999974404% confidence level). The output jitter specification applies to the intrinsic jitter of the PLL, when an input jitter of 30 ps is applied. The external memory interface clock output jitter specifications use a different measurement method and are available in Table 44 on page 52.
- (6) The cascaded PLL specification is only applicable with the following condition: a. Upstream PLL: 0.59Mhz ≤ Upstream PLL BW < 1 MHz b. Downstream PLL: Downstream PLL BW > 2 MHz
- (7) High bandwidth PLL settings are not supported in external feedback mode.
- (8) The external memory interface clock output jitter specifications use a different measurement method, which is available in Table 42 on page 50.
- (9) The VCO frequency reported by the Quartus II software in the PLL Usage Summary section of the compilation report takes into consideration the VCO post-scale counter K value. Therefore, if the counter K has a value of 2, the frequency reported can be lower than the f_{VCO} specification.
- (10) This specification only covers fractional PLL for low bandwidth. The f_{VCO} for fractional value range 0.05 0.95 must be \geq 1000 MHz, while f_{VCO} for fractional value range 0.20 0.80 must be \geq 1200 MHz.
- (11) This specification only covered fractional PLL for low bandwidth. The f_{VC0} for fractional value range 0.05-0.95 must be \geq 1000 MHz.
- (12) This specification only covered fractional PLL for low bandwidth. The f_{VC0} for fractional value range 0.20-0.80 must be \geq 1200 MHz.

DSP Block Specifications

Table 32 lists the Stratix V DSP block performance specifications.

			I	Peforman	ce			
Mode	C1	C2, C2L	12, 12L	C3	13, 13L, 13YY	C4	14	Unit
		Modes ι	ising one	DSP				4
Three 9 x 9	600	600	600	480	480	420	420	MHz
One 18 x 18	600	600	600	480	480	420	400	MHz
Two partial 18 x 18 (or 16 x 16)	600	600	600	480	480	420	400	MHz
One 27 x 27	500	500	500	400	400	350	350	MHz
One 36 x 18	500	500	500	400	400	350	350	MHz
One sum of two 18 x 18(One sum of 2 16 x 16)	500	500	500	400	400	350	350	MHz
One sum of square	500	500	500	400	400	350	350	MHz
One 18 x 18 plus 36 (a x b) + c	500	500	500	400	400	350	350	MHz
		Modes u	sing two l	DSPs	1		•	1
Three 18 x 18	500	500	500	400	400	350	350	MHz
One sum of four 18 x 18	475	475	475	380	380	300	300	MHz
One sum of two 27 x 27	465	465	450	380	380	300	290	MHz
One sum of two 36 x 18	475	475	475	380	380	300	300	MHz
One complex 18 x 18	500	500	500	400	400	350	350	MHz
One 36 x 36	475	475	475	380	380	300	300	MHz

Table 32. Block Performance Specifications for Stratix V DSP Devices (Part 1 of 2)

0h.a.l	Conditions	C1			C2,	C2L, I	2, I2L	C3, I3, I3L, I3YY			C4,14			11
Symbol	Conultions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
Transmitter	•													•
	SERDES factor J = 3 to 10 (9), (11), (12), (13), (14), (15), (16)	(6)	_	1600	(6)	_	1434	(6)	_	1250	(6)	_	1050	Mbps
	$\begin{array}{c} \text{SERDES factor J} \\ \geq 4 \end{array}$													
True Differential I/O Standards	LVDS TX with DPA ⁽¹²⁾ , ⁽¹⁴⁾ , ⁽¹⁵⁾ , ⁽¹⁶⁾	(6)		1600	(6)		1600	(6)	_	1600	(6)	_	1250	Mbps
- f _{HSDR} (data rate)	SERDES factor J = 2,	(6)		(7)	(6)		(7)	(6)		(7)	(6)		(7)	Mbps
	uses DDR Registers	(0)	_	(7)	(0)		(7)	(0)	_	(7)	(0)	_	(7)	wups
	SERDES factor J = 1, uses SDR Register	(6)	_	(7)	(6)	_	(7)	(6)		(7)	(6)		(7)	Mbps
Emulated Differential I/O Standards with Three External Output Resistor Networks - f _{HSDR} (data rate) ⁽¹⁰⁾	SERDES factor J = 4 to 10 (17)	(6)		1100	(6)		1100	(6)		840	(6)		840	Mbps
t _{x Jitter} - True Differential	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	_	_	160	_	_	160			160	_		160	ps
I/O Standards	Total Jitter for Data Rate < 600 Mbps	_	_	0.1	_	_	0.1	_	_	0.1	_	_	0.1	UI
t _{x Jitter} - Emulated Differential I/O Standards	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	_	_	300	_	_	300	_	_	300	_	_	325	ps
with Three External Output Resistor Network	Total Jitter for Data Rate < 600 Mbps	_		0.2			0.2			0.2	_		0.25	UI

Table 36. High-Speed I/O Specifications for Stratix V Devices (1), (2) (Part 2 of 4)

Speed Grade	Min	Max	Unit
C4,I4	8	16	ps

Table 40. DQS Phase Offset Delay Per Setting for Stratix V Devices ^{(1), (2)} (Part 2 of 2)

Notes to Table 40:

(1) The typical value equals the average of the minimum and maximum values.

(2) The delay settings are linear with a cumulative delay variation of 40 ps for all speed grades. For example, when using a -2 speed grade and applying a 10-phase offset setting to a 90° phase shift at 400 MHz, the expected average cumulative delay is [625 ps + (10 × 10 ps) ± 20 ps] = 725 ps ± 20 ps.

Table 41 lists the DQS phase shift error for Stratix V devices.

Table 41. DQS Phase Shift Error Specification for DLL-Delayed Clock (t_{DQS_PSERR}) for Stratix V Devices ⁽¹⁾

Number of DQS Delay Buffers	C1	C2, C2L, I2, I2L	C3, I3, I3L, I3YY	C4,14	Unit
1	28	28	30	32	ps
2	56	56	60	64	ps
3	84	84	90	96	ps
4	112	112	120	128	ps

Notes to Table 41:

(1) This error specification is the absolute maximum and minimum error. For example, skew on three DQS delay buffers in a -2 speed grade is ± 78 ps or ± 39 ps.

Table 42 lists the memory output clock jitter specifications for Stratix V devices.

Clock Network	Parameter	Symbol	C1 C2, C2L, I2, I2L		, 12, 12L	C3, I3, I3L, I3YY		C4,14		Unit	
NELWUIK		-	Min	Max	Min	Max	Min	Max	Min	Max	
	Clock period jitter	t _{JIT(per)}	-50	50	-50	50	-55	55	-55	55	ps
Regional	Cycle-to-cycle period jitter	$t_{\rm JIT(cc)}$	-100	100	-100	100	-110	110	-110	110	ps
	Duty cycle jitter	$t_{JIT(duty)}$	-50	50	-50	50	-82.5	82.5	-82.5	82.5	ps
	Clock period jitter	t _{JIT(per)}	-75	75	-75	75	-82.5	82.5	-82.5	82.5	ps
Global	Cycle-to-cycle period jitter	$t_{\text{JIT(cc)}}$	-150	150	-150	150	-165	165	-165	165	ps
	Duty cycle jitter	$t_{JIT(duty)}$	-75	75	-75	75	-90	90	-90	90	ps

Duty Cycle Distortion (DCD) Specifications

Table 44 lists the worst-case DCD for Stratix V devices.

Table 44. Worst-Case DCD on Stratix V I/O Pins (1)

Symbol	C	1	C2, C2L, I2, I2L		C3, I3, I3L, I3YY		C4,14		Unit	
	Min	Max	Min	Max	Min	Max	Min	Max		
Output Duty Cycle	45	55	45	55	45	55	45	55	%	

Note to Table 44:

(1) The DCD numbers do not cover the core clock network.

Configuration Specification

POR Delay Specification

Power-on reset (POR) delay is defined as the delay between the time when all the power supplies monitored by the POR circuitry reach the minimum recommended operating voltage to the time when the nSTATUS is released high and your device is ready to begin configuration.



For more information about the POR delay, refer to the *Hot Socketing and Power-On Reset in Stratix V Devices* chapter.

Table 45 lists the fast and standard POR delay specification.

Table 45. Fast and Standard POR Delay Specification (1)

POR Delay	Minimum	Maximum	
Fast	4 ms	12 ms	
Standard	100 ms	300 ms	

Note to Table 45:

(1) You can select the POR delay based on the MSEL settings as described in the MSEL Pin Settings section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

JTAG Configuration Specifications

Table 46 lists the JTAG timing parameters and values for Stratix V devices.

Table 46. JTAG Timing Parameters and Values for Stratix V Devices

Symbol	Description	Min	Max	Unit
t _{JCP}	TCK clock period ⁽²⁾	30	—	ns
t _{JCP}	TCK clock period ⁽²⁾	167	—	ns
t _{JCH}	TCK clock high time ⁽²⁾	14	—	ns
t _{JCL}	TCK clock low time ⁽²⁾	14	—	ns
t _{JPSU (TDI)}	TDI JTAG port setup time	2	—	ns
t _{JPSU (TMS)}	TMS JTAG port setup time	3	—	ns

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Table 51 lists the timing parameters for Stratix V devices for FPP configuration when the DCLK-to-DATA[] ratio is more than 1.

Symbol	Parameter	Minimum	Maximum	Units	
t _{CF2CD}	nCONFIG low to CONF_DONE low	—	600	ns	
t _{CF2ST0}	nCONFIG low to nSTATUS low	—	600	ns	
t _{CFG}	nCONFIG low pulse width	2	_	μS	
t _{STATUS}	nSTATUS low pulse width	268	1,506 ⁽²⁾	μS	
t _{CF2ST1}	nCONFIG high to nSTATUS high	—	1,506 ⁽²⁾	μS	
t _{CF2CK} ⁽⁵⁾	nCONFIG high to first rising edge on DCLK	1,506	_	μS	
t _{ST2CK} ⁽⁵⁾	nSTATUS high to first rising edge of DCLK	2	—	μS	
t _{DSU}	DATA [] setup time before rising edge on DCLK	5.5		ns	
t _{DH}	DATA [] hold time after rising edge on DCLK	N-1/f _{DCLK} ⁽⁵⁾		S	
t _{CH}	DCLK high time	$0.45 imes 1/f_{MAX}$		S	
t _{CL}	DCLK low time	$0.45\times1/f_{MAX}$		S	
t _{CLK}	DCLK period	1/f _{MAX}		S	
ſ	DCLK frequency (FPP ×8/×16)	—	125	MHz	
f _{MAX}	DCLK frequency (FPP ×32)	—	100	MHz	
t _R	Input rise time	—	40	ns	
t _F	Input fall time	—	40	ns	
t _{CD2UM}	CONF_DONE high to user mode ⁽³⁾	175	437	μS	
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	_	_	
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t_{CD2CU} + (8576 × CLKUSR period) ⁽⁴⁾	_	_	

Notes to Table 51:

- (1) Use these timing parameters when you use the decompression and design security features.
- (2) You can obtain this value if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.
- (3) The minimum and maximum numbers apply only if you use the internal oscillator as the clock source for initializing the device.
- (4) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (5) N is the ${\tt DCLK}\mbox{-to-DATA}$ ratio and $f_{{\tt DCLK}}$ is the ${\tt DCLK}$ frequency the system is operating.
- (6) If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.

Table 54 lists the PS configuration timing parameters for Stratix V devices.

Table 54. PS Timing Parameters for Stratix V Devices

Symbol	Parameter	Minimum	Maximum	Units
t _{CF2CD}	nCONFIG low to CONF_DONE low	—	600	ns
t _{CF2ST0}	nCONFIG low to nSTATUS low	—	600	ns
t _{CFG}	nCONFIG low pulse width	2	—	μS
t _{status}	nSTATUS low pulse width	268	1,506 ⁽¹⁾	μS
t _{CF2ST1}	nCONFIG high to nSTATUS high	—	1,506 ⁽²⁾	μS
t _{CF2CK} ⁽⁵⁾	nCONFIG high to first rising edge on DCLK	1,506	—	μS
t _{ST2CK} ⁽⁵⁾	nSTATUS high to first rising edge of DCLK	2	—	μS
t _{DSU}	DATA [] setup time before rising edge on DCLK	5.5	_	ns
t _{DH}	DATA [] hold time after rising edge on DCLK	0	_	ns
t _{CH} DCLK high time		$0.45\times 1/f_{MAX}$	—	S
t _{CL} DCLK low time		$0.45\times 1/f_{MAX}$	—	S
t _{CLK}	DCLK period	1/f _{MAX}	_	S
f _{MAX}	DCLK frequency	—	125	MHz
t _{CD2UM}	CONF_DONE high to user mode ⁽³⁾	175	437	μS
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	—	_
t_{CD2UMC} CONF_DONE high to user mode with CLKUSR option on		$\begin{array}{c} t_{\text{CD2CU}} + \\ (8576 \times \text{CLKUSR} \\ \text{period}) \ \ ^{(4)} \end{array}$	_	_

Notes to Table 54:

(1) This value is applicable if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.

(2) This value is applicable if you do not delay configuration by externally holding the nSTATUS low.

(3) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.

(4) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the "Initialization" section.

(5) If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.

Initialization

Table 55 lists the initialization clock source option, the applicable configuration schemes, and the maximum frequency.

Table 55. Initialization Clock Source Option and the Maximu

Initialization Clock Source	Configuration Schemes	Maximum Frequency	Minimum Number of Clock Cycles ⁽¹⁾
Internal Oscillator	AS, PS, FPP	12.5 MHz	
CLKUSR	AS, PS, FPP ⁽²⁾	125 MHz	8576
DCLK	PS, FPP	125 MHz	

Notes to Table 55:

(1) The minimum number of clock cycles required for device initialization.

(2) To enable CLKUSR as the initialization clock source, turn on the Enable user-supplied start-up clock (CLKUSR) option in the Quartus II software from the General panel of the Device and Pin Options dialog box.

Table 60. Glossary (Part 2 of 4)

Letter	Subject	Definitions
G		
Н	_	_
Ι		
J	J JTAG Timing Specifications	High-speed I/O block—Deserialization factor (width of parallel data bus). JTAG Timing Specifications: TMS
K L M N O	_	_
Ρ	PLL Specifications	Diagram of PLL Specifications (1)
Q		_
	1	